



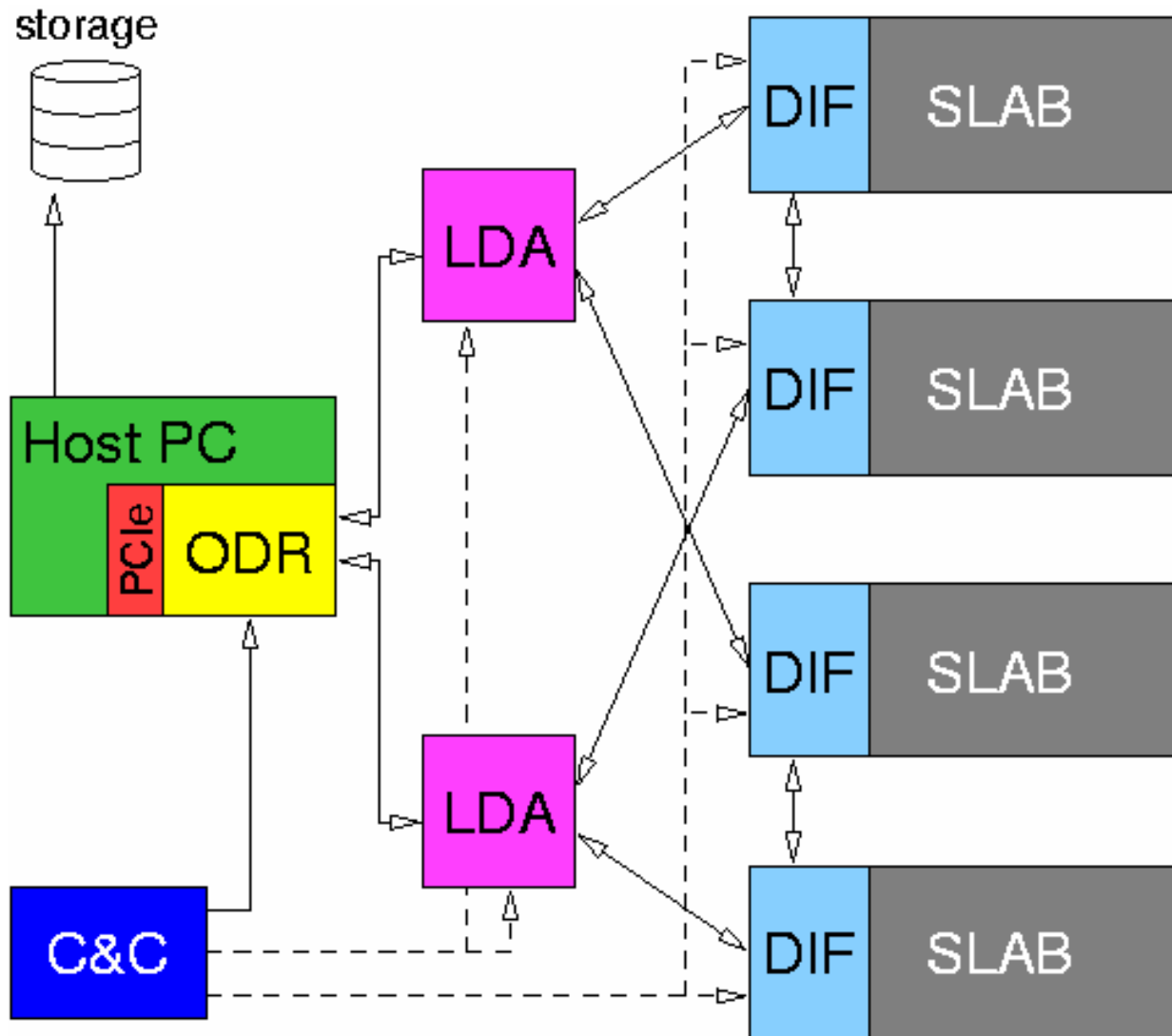
CALICE DAQ Developments

DAQ overview

DIF functionality and implementation

EUDET Prototype development path

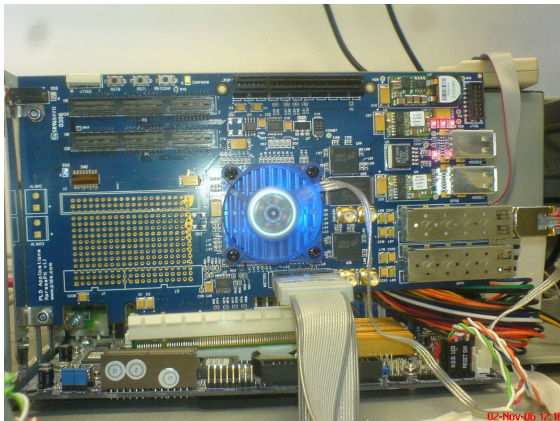
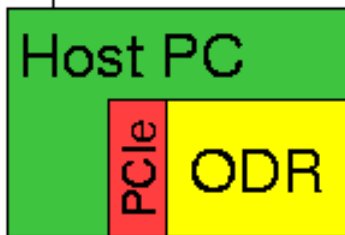
DAQ architecture



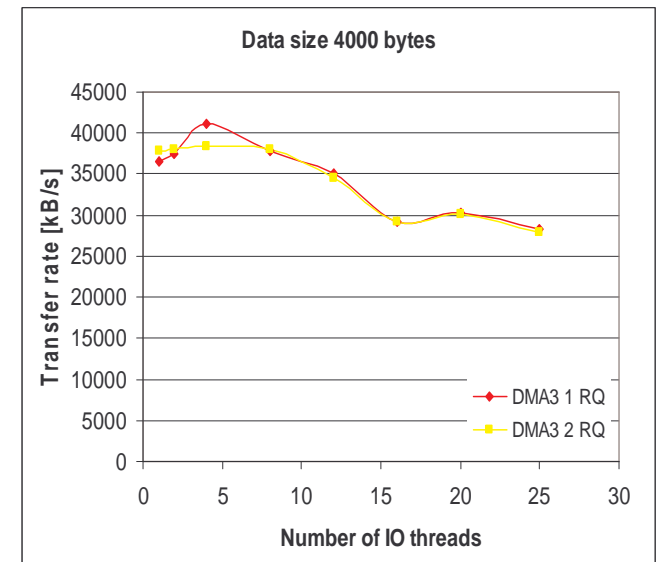
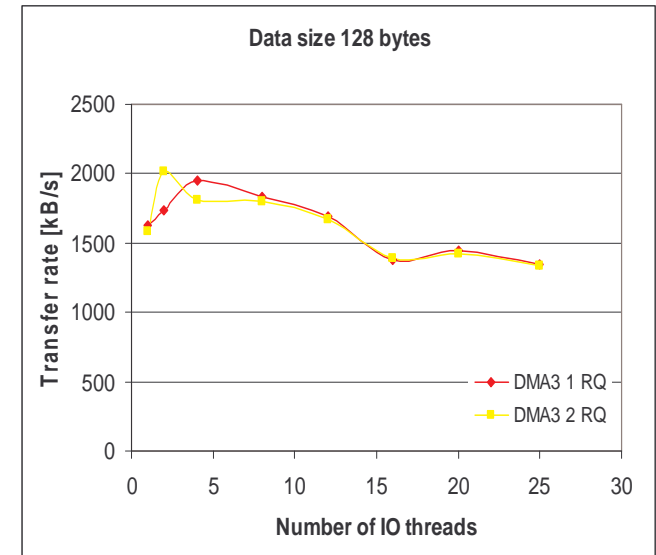
- Slab hosts VFE chips
- DIF connected to Slab
- LDA servicing DIFs
- LDAs read out by ODR
- PC hosts ODR, through PCIeexpress
- C&C routes clock, controls

ODR and Data Rates

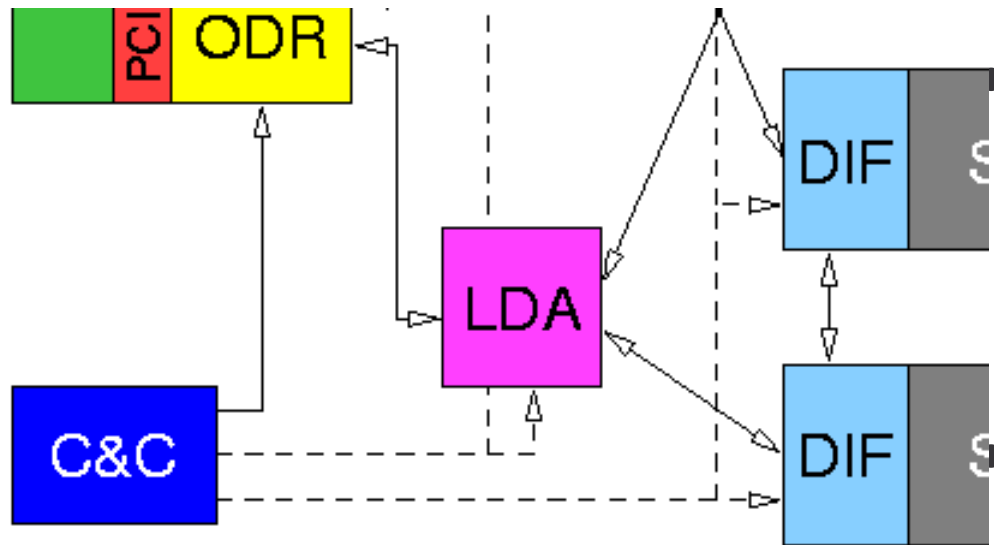
storage



- ODR is a commercial FPGA board with PCIe interface
(Virtex4-FX100, PCIe 8x, etc.)
- Custom firm- and software
- DMA driver pulls data off the onboard RAM, writes to disk
- Performance studies & optimisation



Clock & Controls Distribution

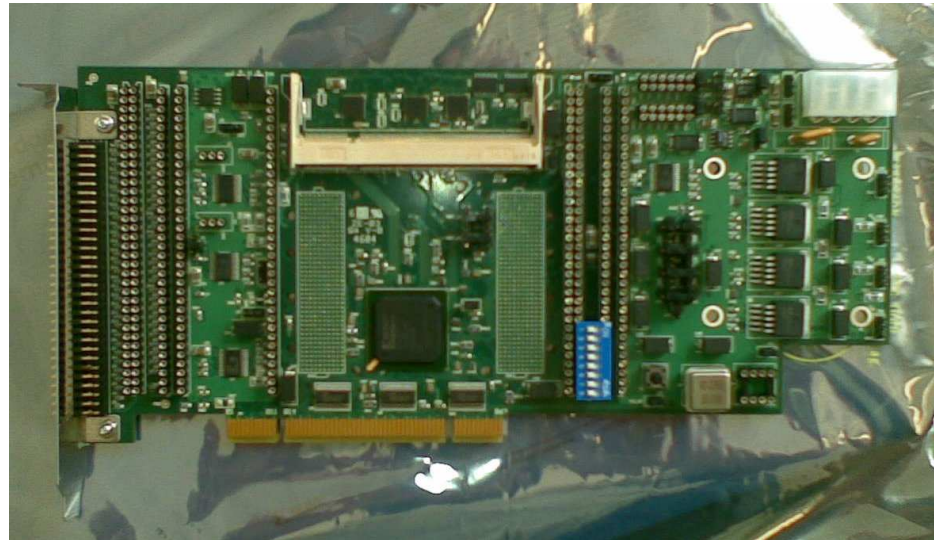
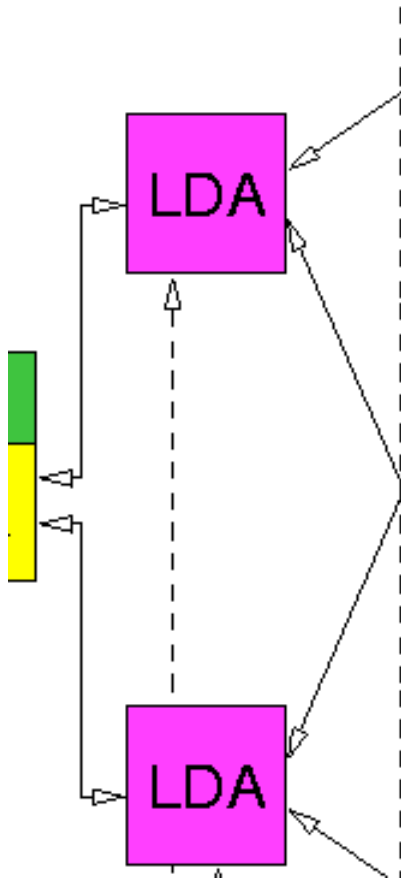


C&C unit provides machine clock and fast signals to ODR, LDA (and DIF?)

Clock jitter requirement seems not outrageous (at the moment)

- Fast Controls: encoded through the LDA-DIF link
- Low-latency fast signals: distributed 'directly'

LDA and link to ODR

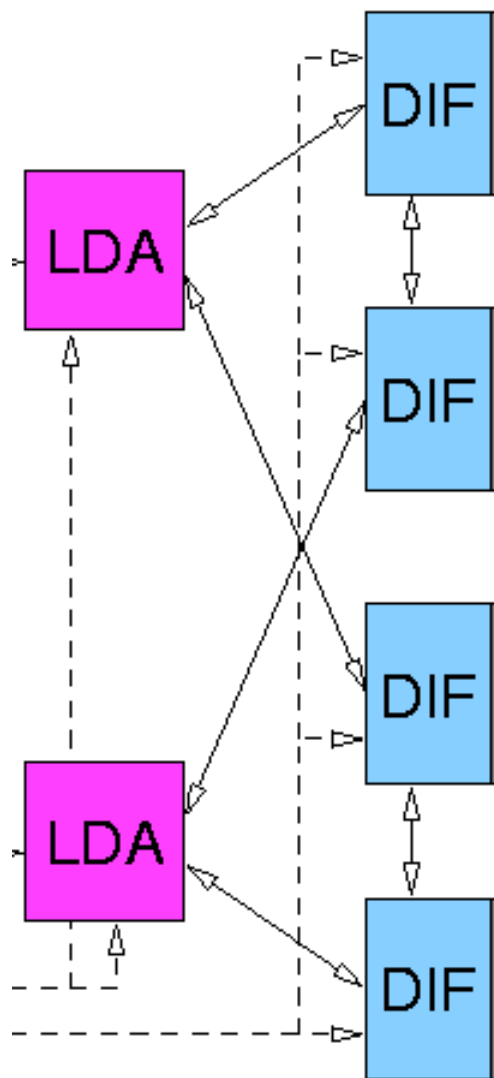


- Enterpoint Xilinx Spartan3 based dev. board
- RAM & lots of I/O (including PCI)

1st Prototype is again a commercial FPGA board with custom firmware and hardware add-ons:

- Gbit ethernet and Glink Rx/Tx for ODR link -probably optical
- Many links towards DIFs

LDA-DIF link



LDA-DIF link:

- Serial link running at multiple of machine clock
- 50Mbps (raw) bandwidth minimum
- robust encoding (8B/10B or alike)
- anticipating 8...16 DIFs on an LDA, bandwidth permitting
- LDAs serve even/odd DIFs for redundancy

LDA-DIF physical interface

	Gnd	2	1	Clk+	Pair1 (STP)
	DL2D+	4	3	Clk-	
Pair2 (STP)	DL2D-	6	5	Gnd	Pair3 (STP)
	Gnd	8	7	DD2L+	
	SpD2L+	10	9	DD2L-	Pair4 (STP)
	SpD2L-	12	11	Gnd	
	Pow2	14	13	Pow1	Pair5 (UTP)
	SpL2D-	16	15	SpL2D+	
	Pow3	18	17	Gnd	
			19	Pow4	

Possible Pinout for HDMI

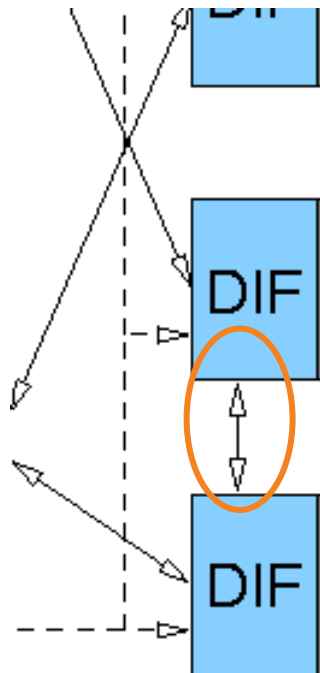
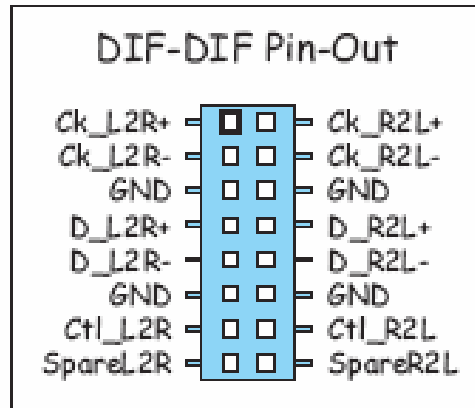
(Based on SAMTEC HPDPI
cable signal designation)

clock
data
control
spare data
spare control

LDA-DIF link physical form factor:

- Differential signals on shielded twisted pairs
- Few single-ended control lines
- HDMI connectors and cabling: high quality, commercially available

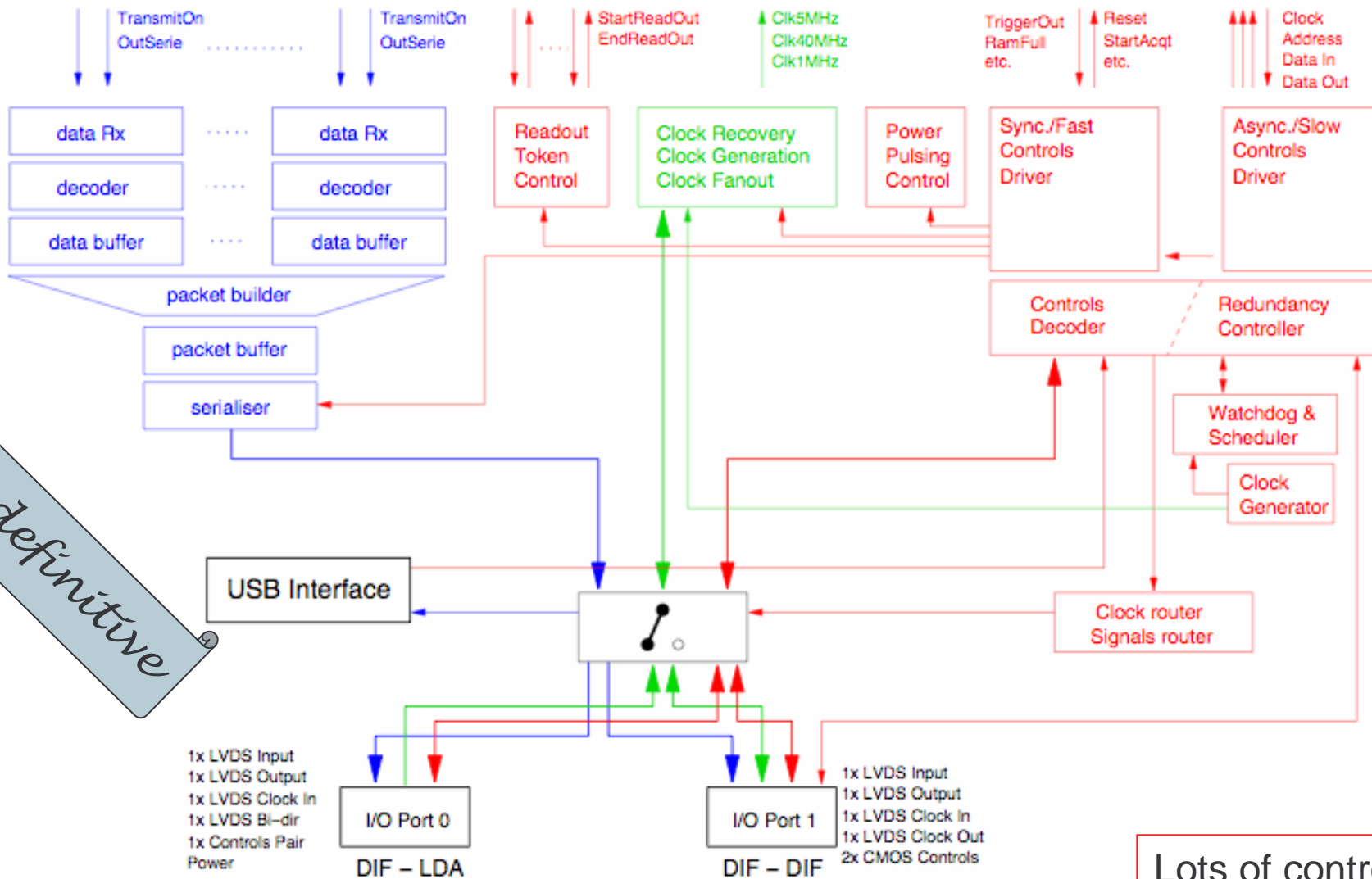
DIF-DIF link



- Redundancy against loss of LDA link
- Provides differential signals:
 - Clock in both directions
 - Data and Control connections
 - Two spares: one each direction
- Plus two single-ended control lines
- Single LDA-DIF link bandwidth sufficiently large for data of two DIFs

Draft DIF block diagram

SLAB



not definitive

Lots of controls....

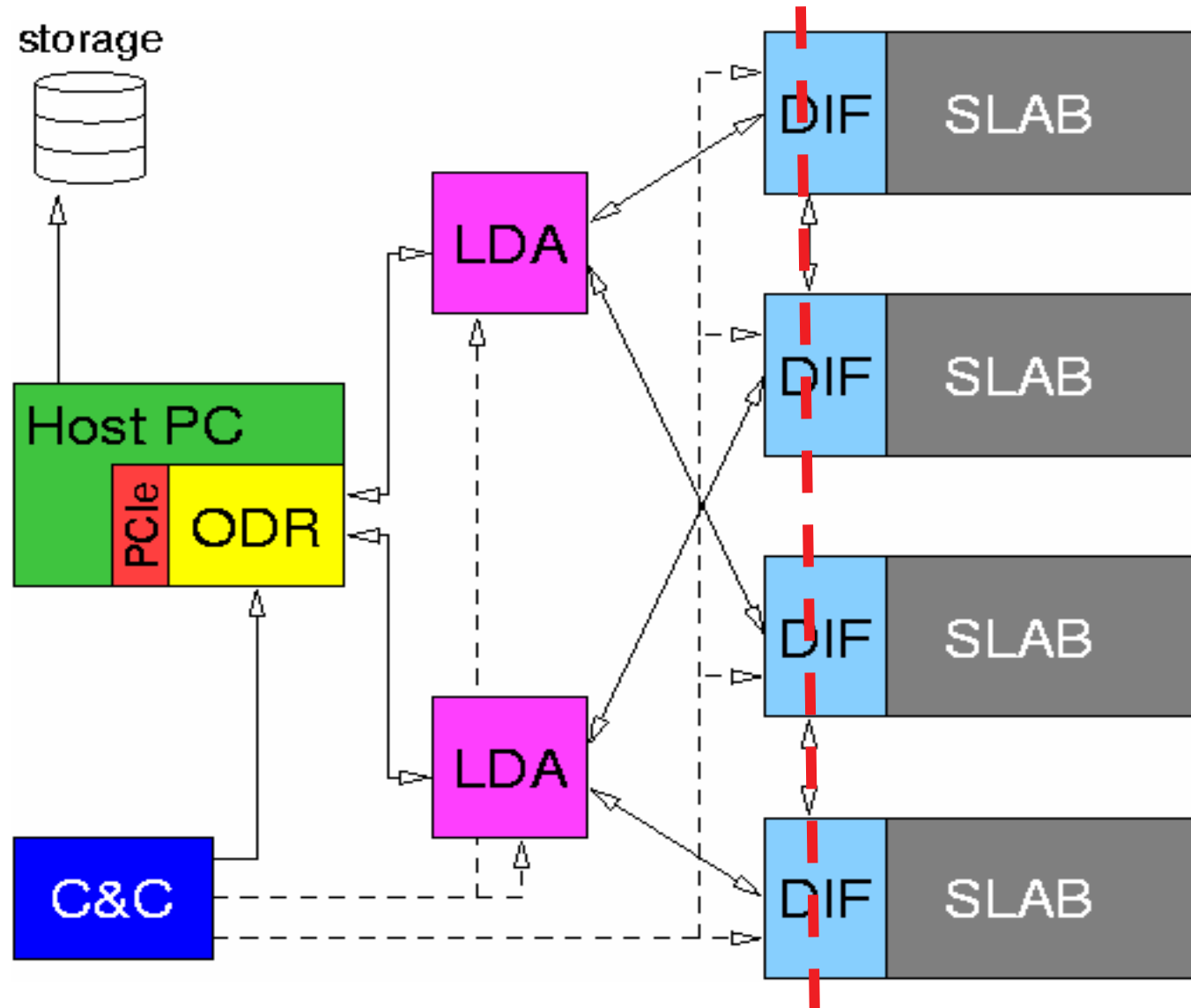
DIF Functionality

- Receive, regenerate and distribute clocks
- Receive, buffer, package and send data from VFE to LDA
- Receive and decode incoming commands and issue corresponding signals
- Control the DIF-DIF redundancy connection
- Receive, decode and distribute slow control commands
- Control power pulsing and provide watchdog functionality
- Provide an USB interface for stand-alone running and debugging
-on top of that: all the things we did not think of so far

DIF implementation

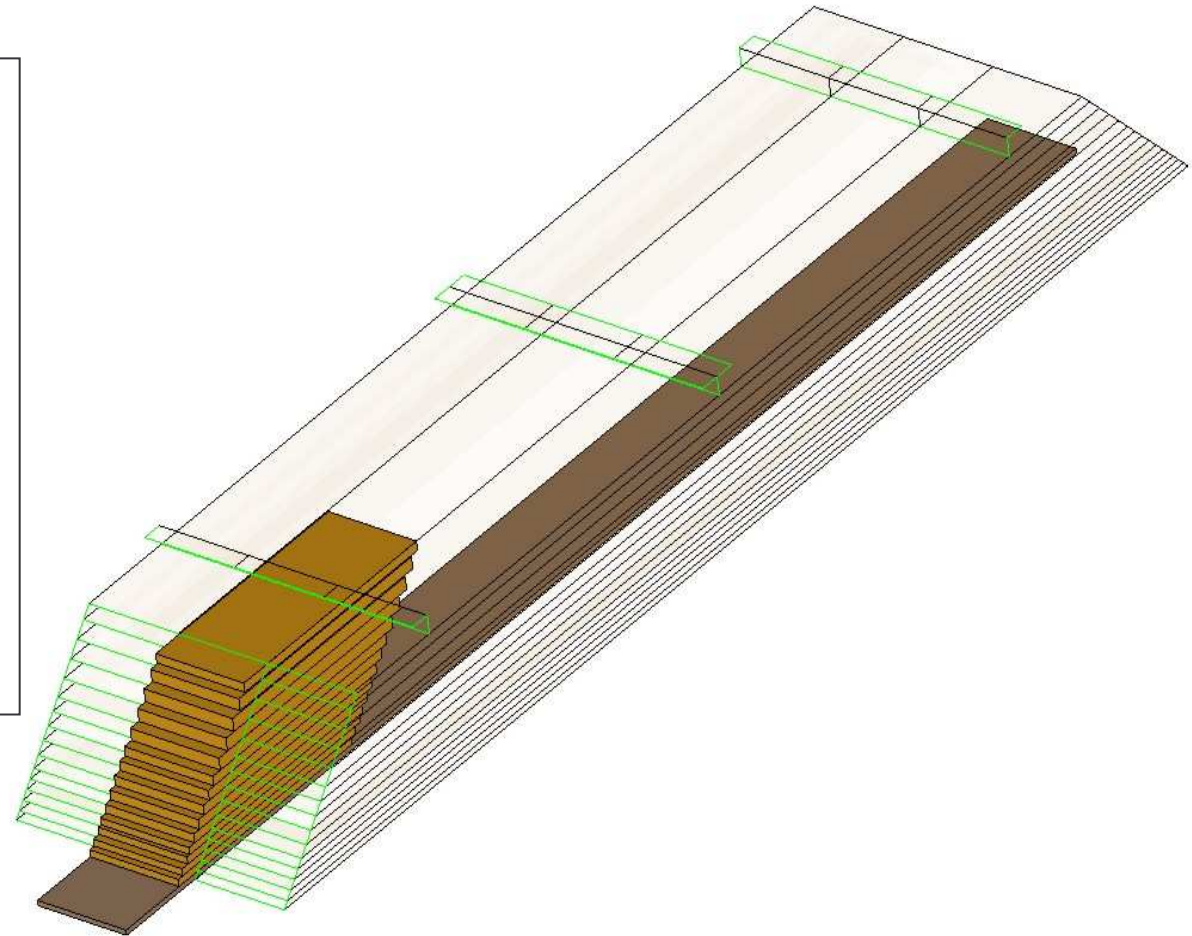
- The Slab is an integral part of the detector
- The LDA and ODR are transparent wrt detector type
- The DIF and its interface to the slab is detector-specific
- Large parts of the DIF firmware *can/should/must* be generalised
- *DIF hardware should support firmware* to profit from common developments
- DIF working group to address common problems and share knowledge, experience, and VHDL code

Opportunity to memorise the acronyms:



The EUDET prototype

- Full stack: 15 slabs, instrumented on both sides
- As close to CALICE technology as reasonably possible



Prototype development

NOW

2008

2009

HaRDROC chip v1
Testbeam DAQ

HaRDROC chip v2

New DAQ v1

EUDET proto:
detector + DAQ

Technology prototype for physics results

EUDET module is quite a large and complex object.

Keep future production in mind:

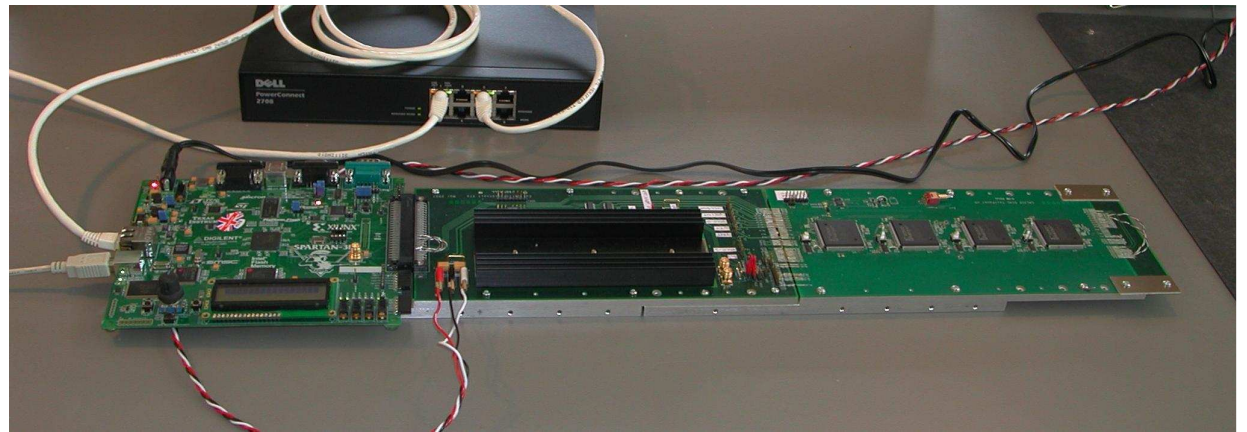
- large objects are assemblies of smaller objects
- develop testable objects

Many technology options require even more R&D:

- power consumption
- data rate: speed vs. power
- noise
- etc.

R&D for the EUDET prototype

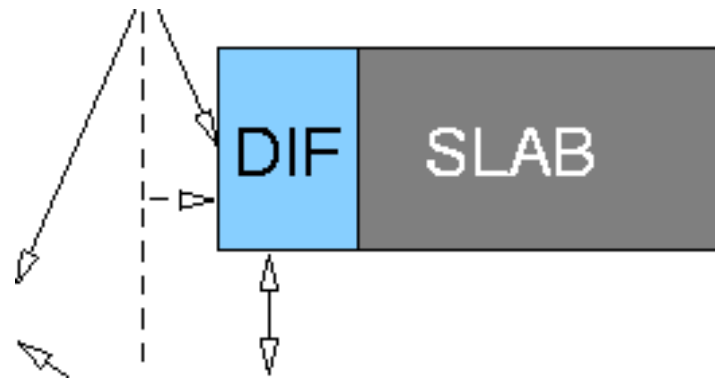
- Proto-slab:
 - FPGA for VFES
 - provisional 'DIF' for ECAL



- Tests of signal distribution along long PCB lines: signal deterioration, termination options, speed, etc.
- Identification of possible issues with many (pseudo)VFE chips on long transmission paths
- Familiarise with VFE readout architecture

R&D for the EUDET prototype

More to come.....



...but let's look at the DIF design first